

Ceramic Plate Series Thermoelectric Cooler

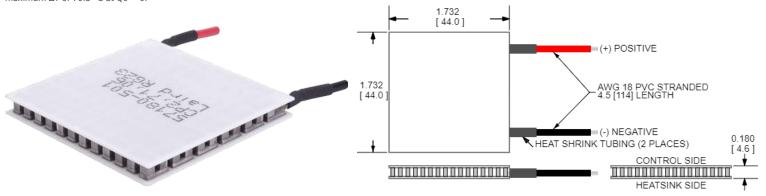
The CP2-71-06-L1-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 65.9 Watts when $\Delta T=0$ and a maximum ΔT of 70.5 °C at Qc =0.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision

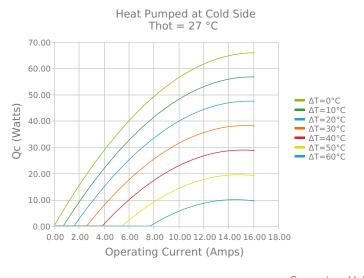


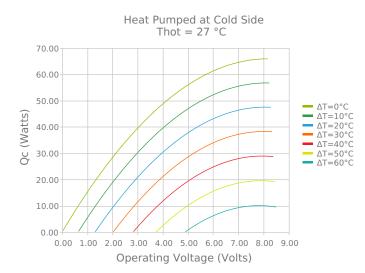
CERAMIC MATERIAL: Al₂O₃ SOLDER CONSTRUCTION: 138°C, BiSn

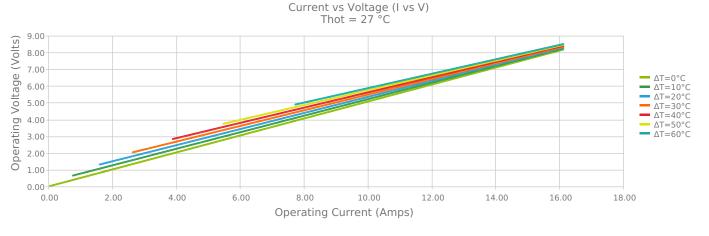
INCHES [MM]

ELECTRICAL AND THERMAL PERFORMANCE

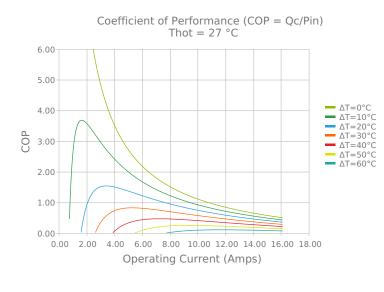
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

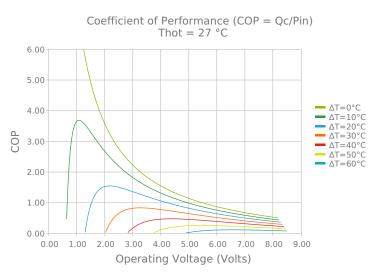


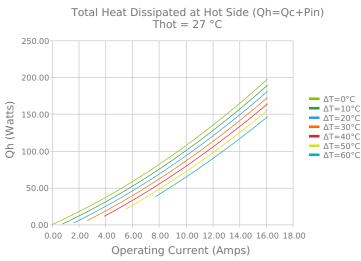


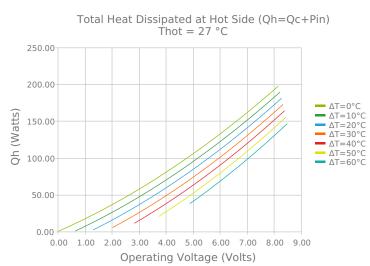


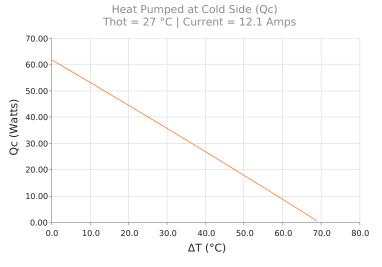


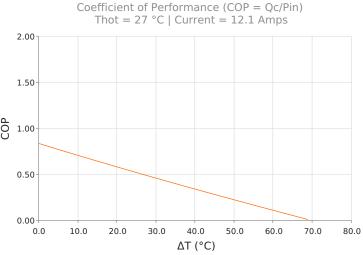














SPECIFICATIONS*

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ ATmax)

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

27.0 °C	35.0 °C	50.0 °C
65.9 Watts	67.9 Watts	71.4 Watts
70.5°C	73.5°C	78.8°C
14.2 Amps	14.2 Amps	14.0 Amps
7.8 Volts	8.1 Volts	8.6 Volts
0.51 Ohms	0.53 Ohms	0.57 Ohms
80 °C		
38.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	4.572 ±0.025 mm 0.180 ± 0.0010 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
	None	No		No sealing specified

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

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^{*} Specifications reflect thermoelectric coefficients updated March 2020